USP-8810 Power Dissipation

Power dissipation data for the USP-8810 is shown in this page. The value of power dissipation varies with the mount board conditions. Please use this data as the reference data taken in the following condition.

1. Measurement Condition
   Condition: Mount on a board
   Ambient: Natural convection
   Soldering: Lead (Pb) free
   Board: Copper foil 4 layer

   Demenshin: 76.2mm × 114.3mm (about 8700mm² in one side)
   1st inner layer: 50mm × 50mm connection with heat sink
   2nd inner layer: 70mm × 70mm connection with heat sink
   3rd inner layer: 70mm × 70mm connection with heat sink
   4th inner layer: 50mm × 50mm connection with heat sink

   Material: Glass Epoxy (FR-4)
   Thickness: 1.6mm
   Through-hole: φ0.2mm 60pcs

2. Power Dissipation vs Ambient temperature

<table>
<thead>
<tr>
<th>Ambient Temperature (°C)</th>
<th>Power Dissipation (Pd (mW))</th>
<th>Thermal Resistance (°C/W)</th>
</tr>
</thead>
<tbody>
<tr>
<td>25</td>
<td>1400</td>
<td></td>
</tr>
<tr>
<td>85</td>
<td>560</td>
<td>71.43</td>
</tr>
</tbody>
</table>

Pd vs. Ta

Power Dissipation (Pd (mW))

Ambient Temperature (Ta (°C))